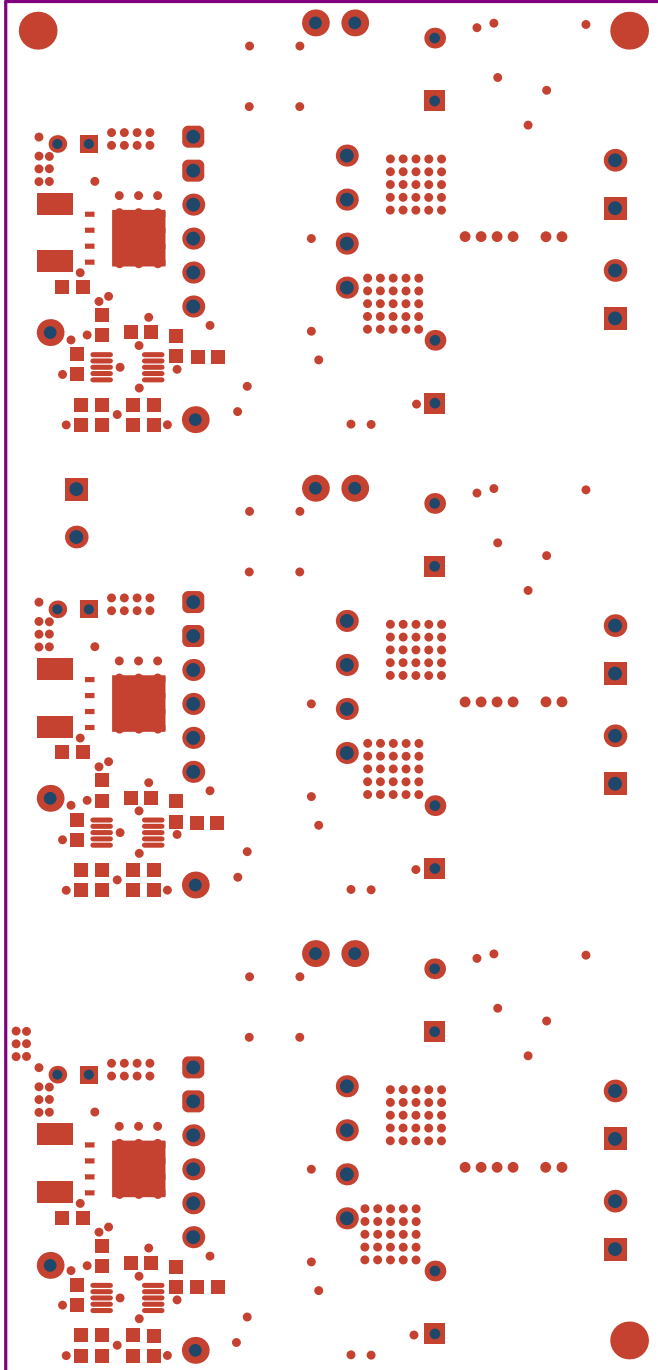
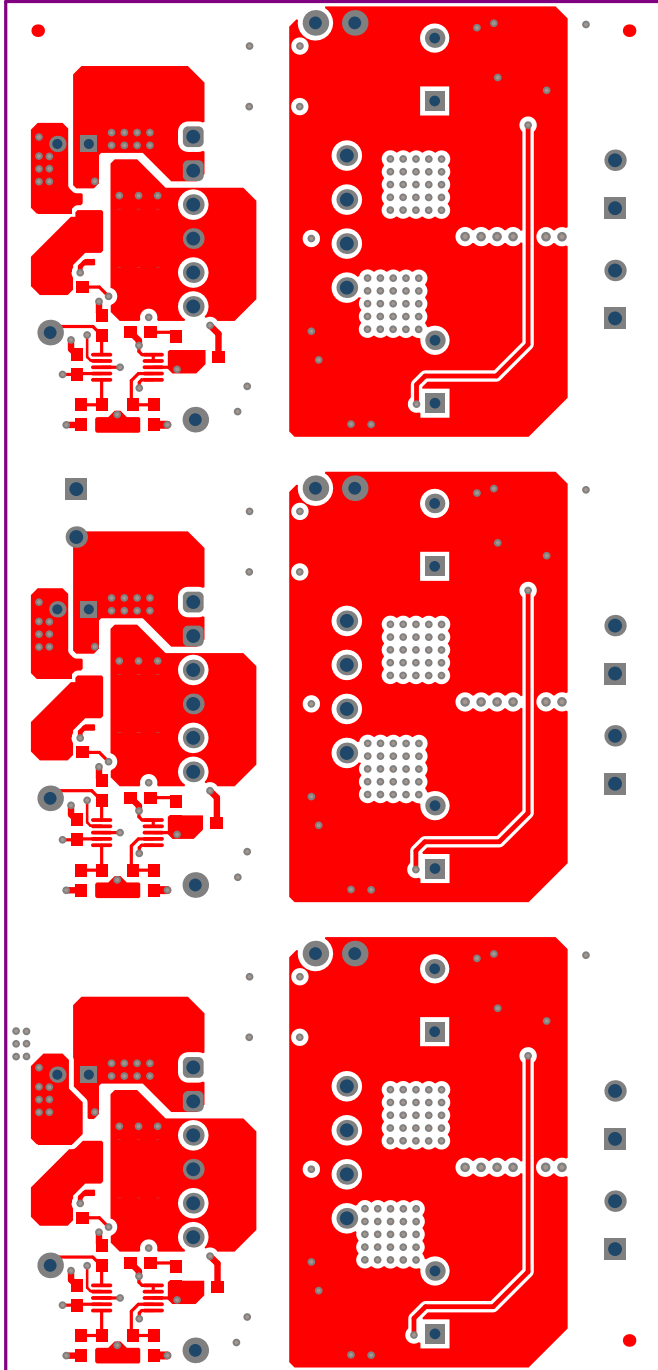


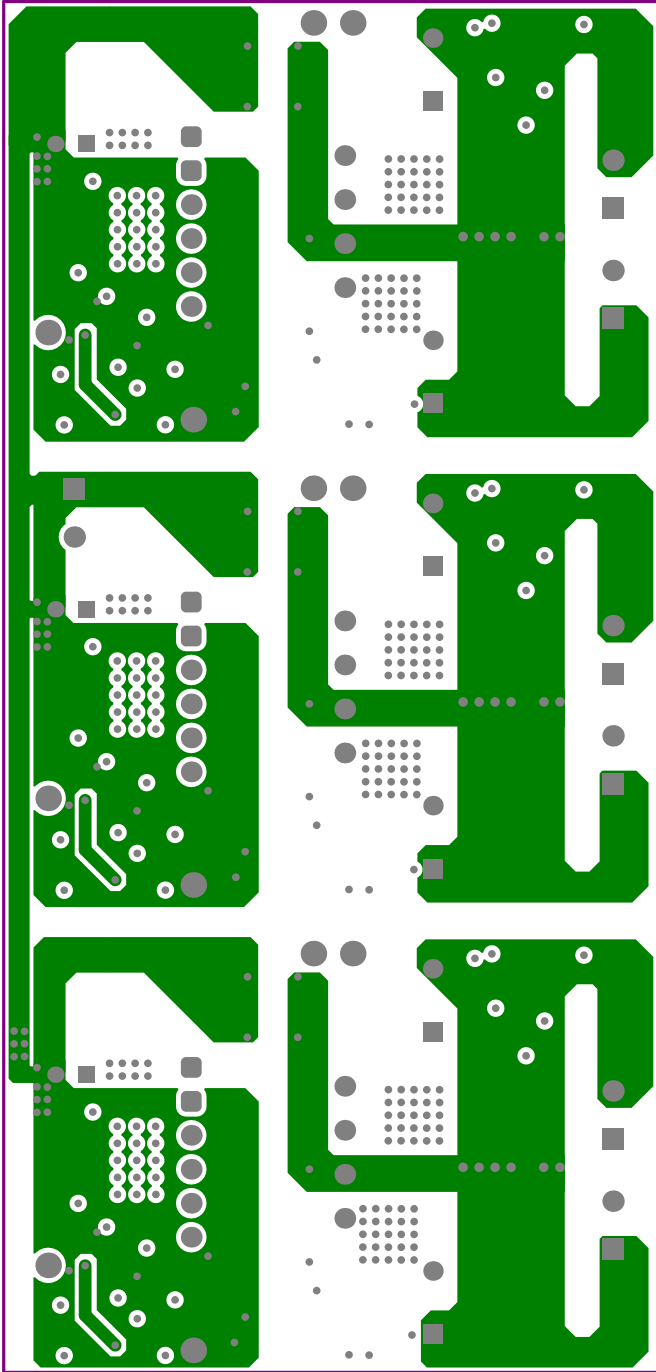
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01592	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01592		
PLOT NAME = Top Overlay	GENERATED : 4/9/2018	10:40:35 AM	TEXAS INSTRUMENTS



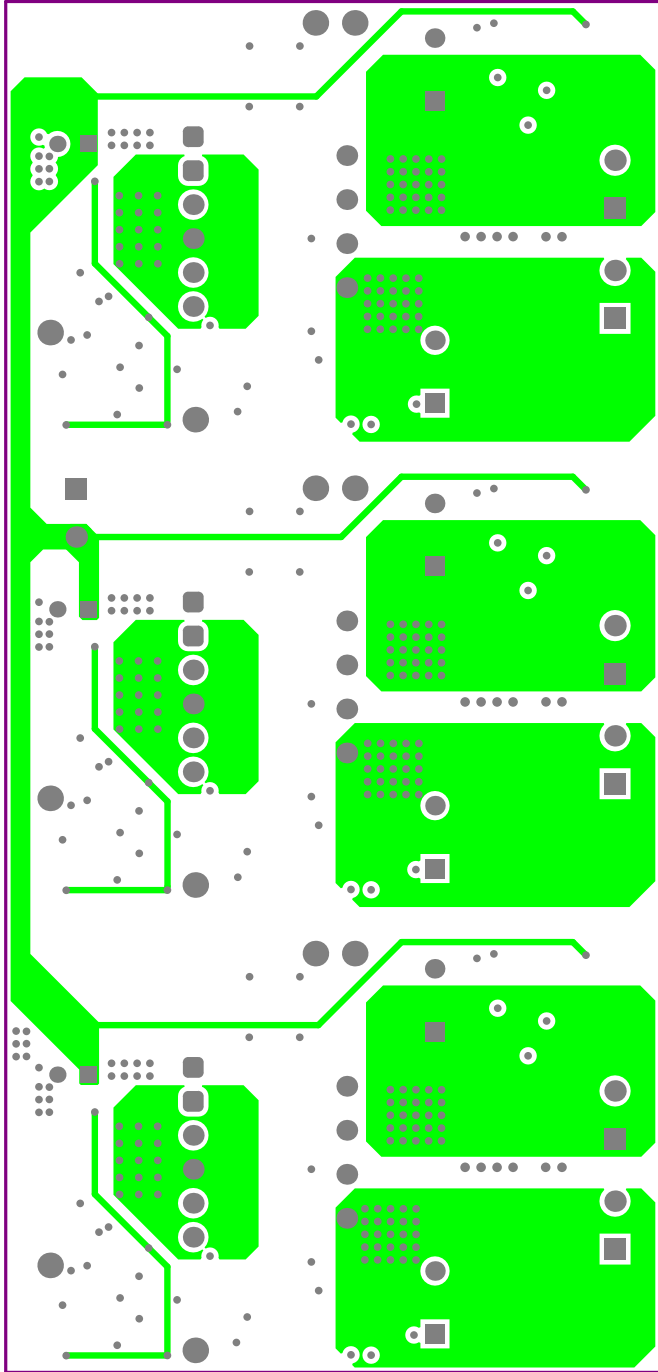
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01592	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01592		
PLOT NAME = Top Solder Mask	GENERATED : 4/9/2018	10:40:35 AM	TEXAS INSTRUMENTS



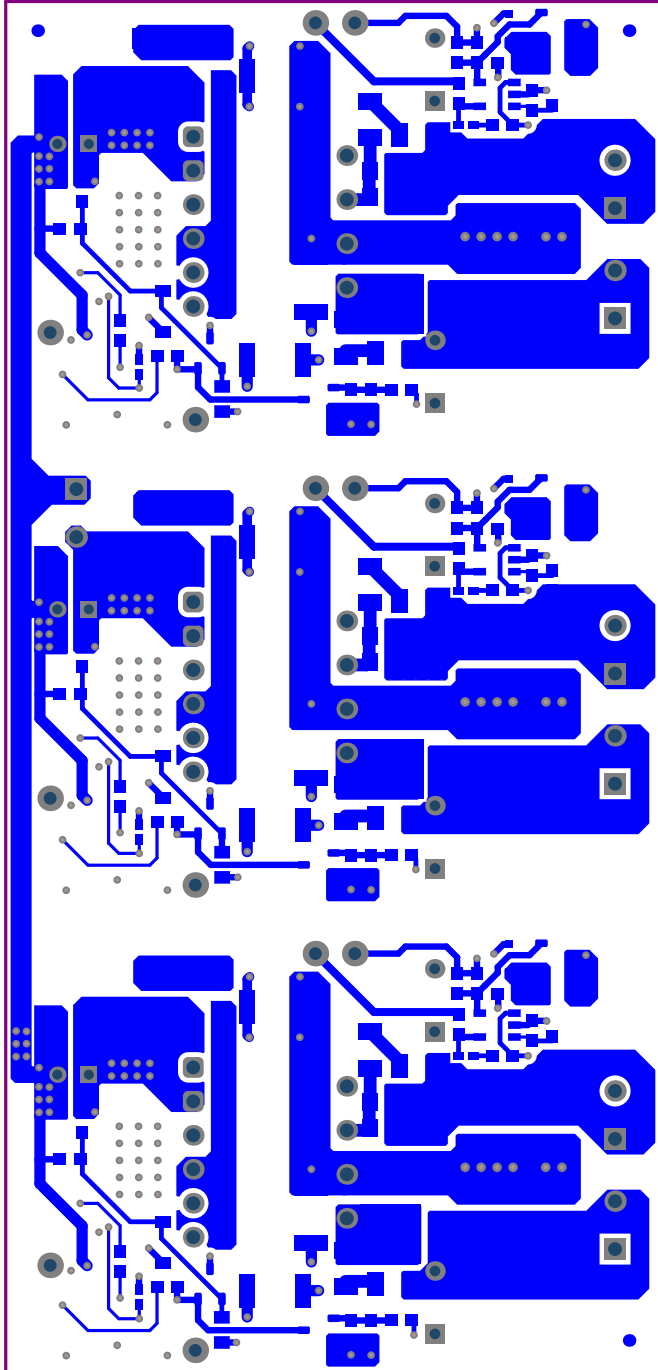
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01592	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01592		
PLOT NAME = Top Layer	GENERATED : 4/9/2018	10:40:35 AM	TEXAS INSTRUMENTS



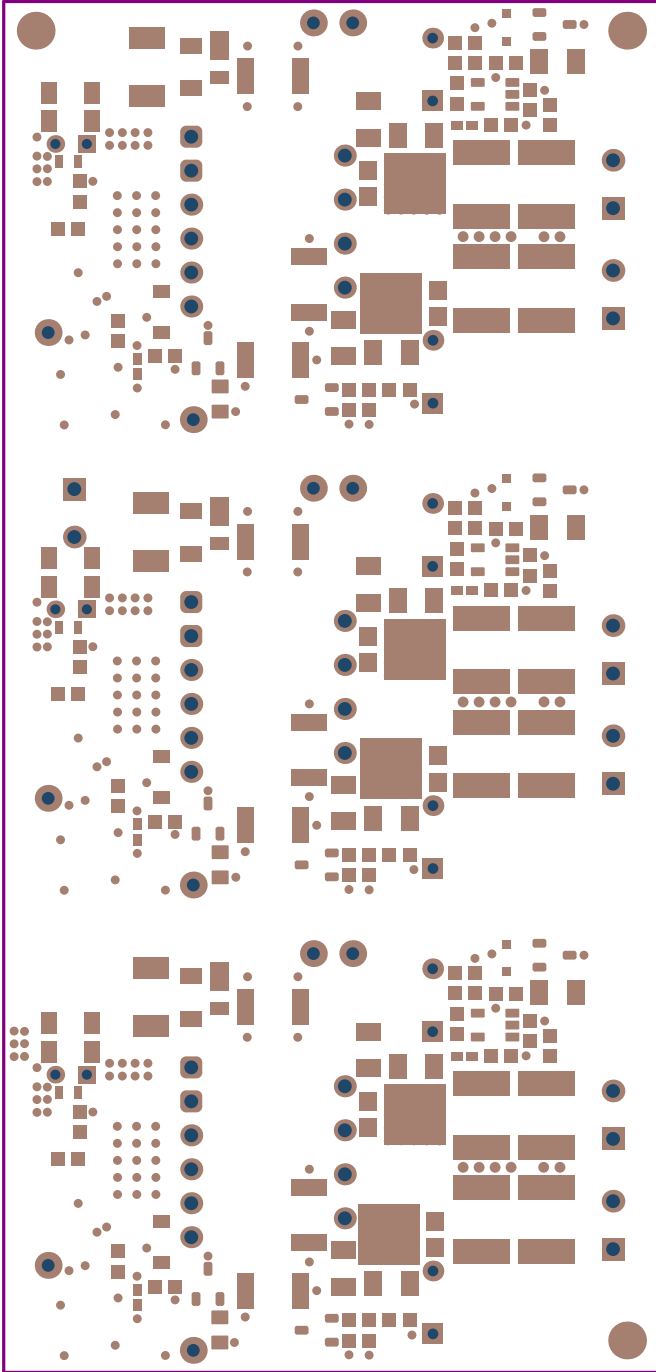
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01592	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = GND	TID #: TIDA-01592		
PLOT NAME = Signal 1	GENERATED : 4/9/2018	10:40:35 AM	TEXAS INSTRUMENTS



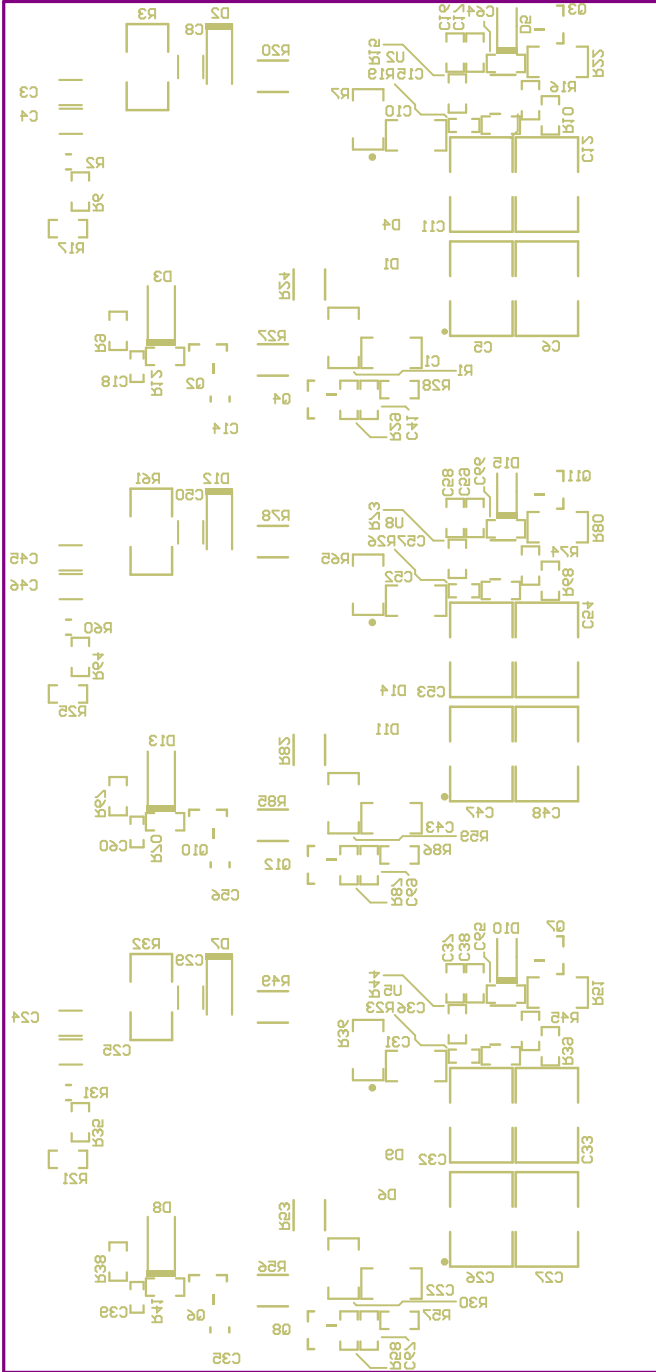
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01592	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = PWR	TID #: TIDA-01592		
PLOT NAME = Signal 2	GENERATED : 4/9/2018	10:40:35 AM	TEXAS INSTRUMENTS



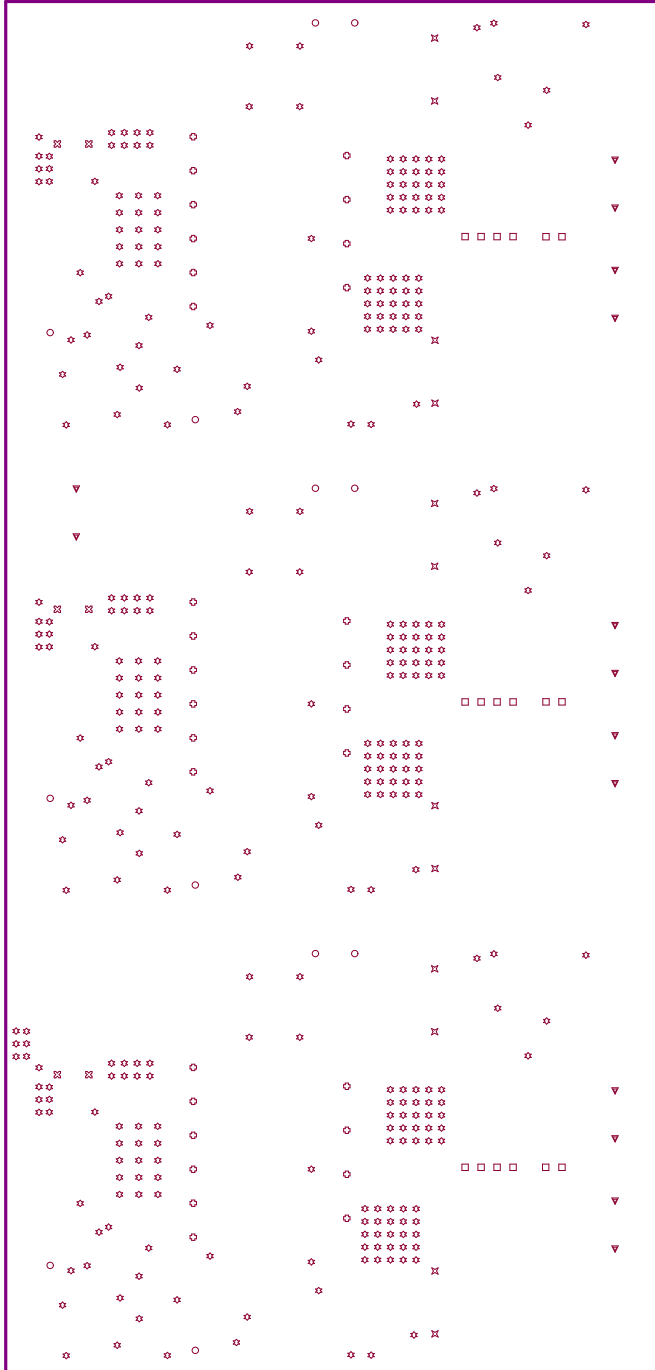
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01592	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01592		
PLOT NAME = Bottom Layer	GENERATED : 4/9/2018	10:40:35 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01592	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01592		
PLOT NAME = Bottom Solder Mask	GENERATED : 4/9/2018	10:40:36 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01592	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01592		
PLOT NAME = Bottom Overlay	GENERATED : 4/9/2018	10:40:36 AM	TEXAS INSTRUMENTS

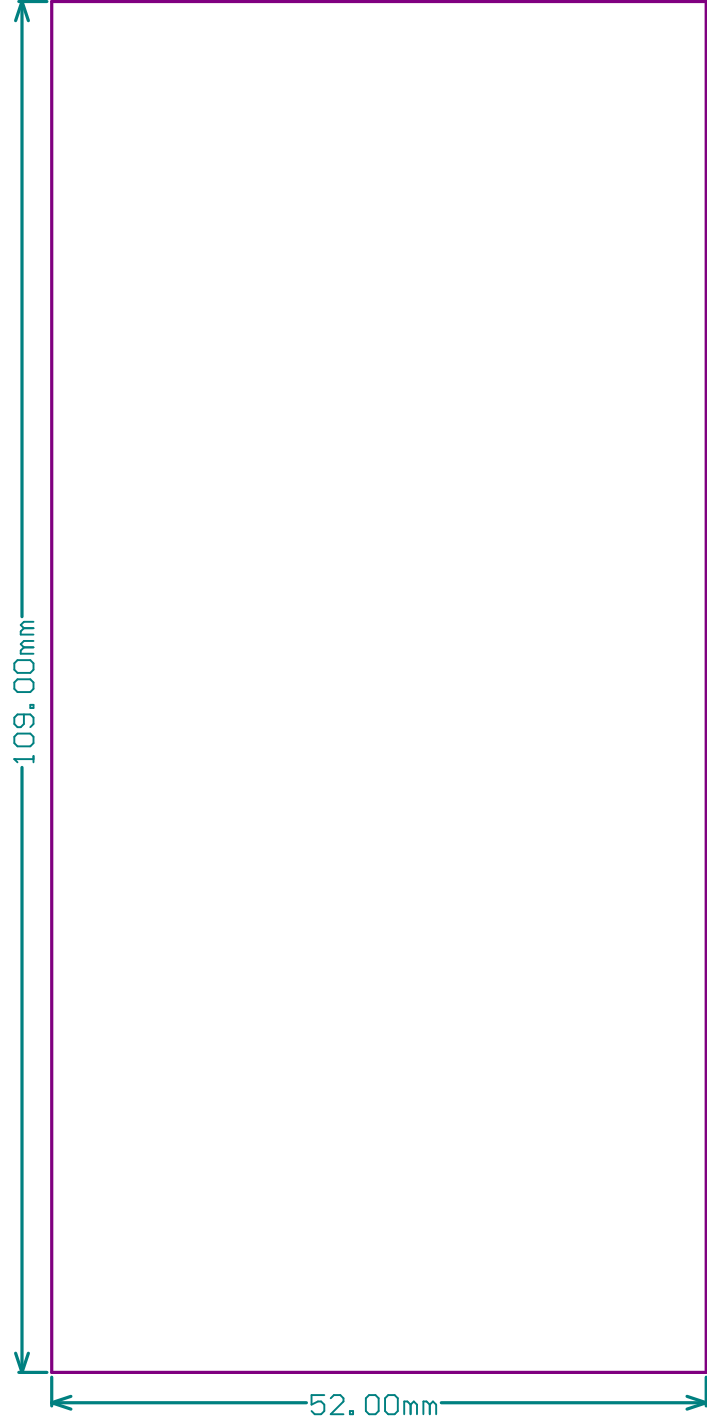


Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair
⊗	6	31.50mil (0.800mm)	PTH	Round	Top Layer - Bottom Layer
⊗	12	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer
○	12	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer
▽	14	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer
□	18	15.00mil (0.381mm)	PTH	Round	Top Layer - Bottom Layer
⊕	30	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer
⊗	348	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer
	440 Total				

DRILL TABLE
 FOR 12MIL DRILL +0/-12MIL
 FOR PTH DRILL +/-3MIL

NOTE:
 This is not an Impedance controlled board.

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01592	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01592		
PLOT NAME = Drill Drawing	GENERATED : 4/9/2018	10:40:36 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01592	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01592		
PLOT NAME = Board Dimensions	GENERATED : 4/9/2018	10:40:38 AM	TEXAS INSTRUMENTS

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